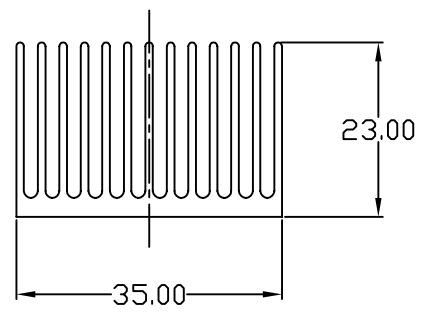
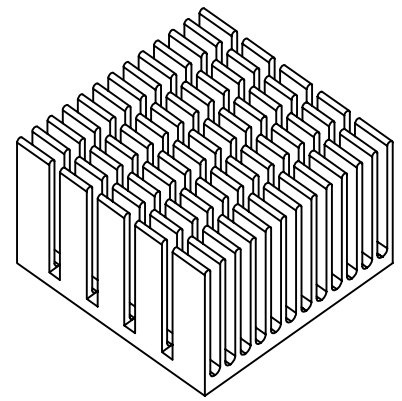
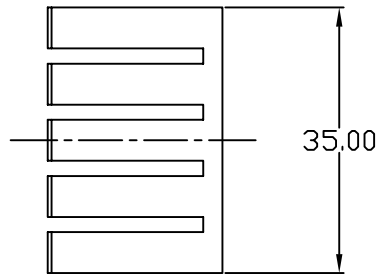
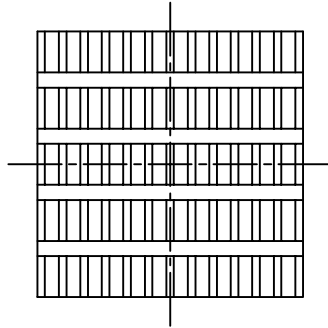
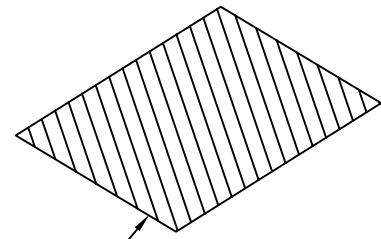


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Thermal Interface Material:  
 Bondply 108 35 x 35mm



HND3501-B Is Old Cofan Part #

No	P/N	Description	Qty
③	70-1037	Tape, Bondply 105:26x26mm	1PC
②	20-1100	Bare HeatSink	1PC
①	30-1916	20-1100 H/S with TAPE	1Set

DO NOT SCALE DRAWING  
 UNLESS OTHERWISE SPECIFIED  
 DIMENSIONS ARE IN MILLIMETRE  
 TOLERANCES ARE:  
 1 PLACE .X ± 0.4  
 2 PLACE .XX ± 0.25  
 3 PLACE .XXX ± 0.13  
 ANGLES EXCEPT 90° ± 1°  
 MAXIMUM SURFACE ROUGHNESS 3.15

MATERIAL: AL 6063-T5	NOKIA DRAWING NUMBER: -	 46177 WARM SPRINGS BLVD FREMONT, CA 94539		
FINISH: Black Anodize	NOKIA PART NUMBER: ----	NAME: HEAT SINK 35 X 35 X 23MM		
DRAWN BY: Dan	COFAN DRAWING NUMBER:	SCALE: 1:1	CUS REV: -	COF REV: 01
APPR BY:	COFAN PART NUMBER: 30-1916	SHEET: 1 OF 1	DATE DRAWN: May-16-2008	